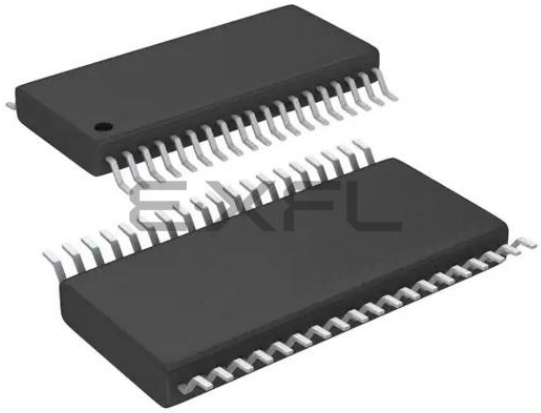


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc866l-4fri-bc

1 Summary of Features

- High-performance XC800 Core
  - compatible with standard 8051 processor
  - two clocks per machine cycle architecture (for memory access without wait state)
  - two data pointers
- On-chip memory
  - 8 Kbytes of Boot ROM
  - 256 bytes of RAM
  - 512 bytes of XRAM
  - 4/8/16 Kbytes of Flash; or
    8/16 Kbytes of ROM, with additional 4 Kbytes of Flash
    (includes memory protection strategy)
- I/O port supply at 3.3 V/5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(further features are on next page)

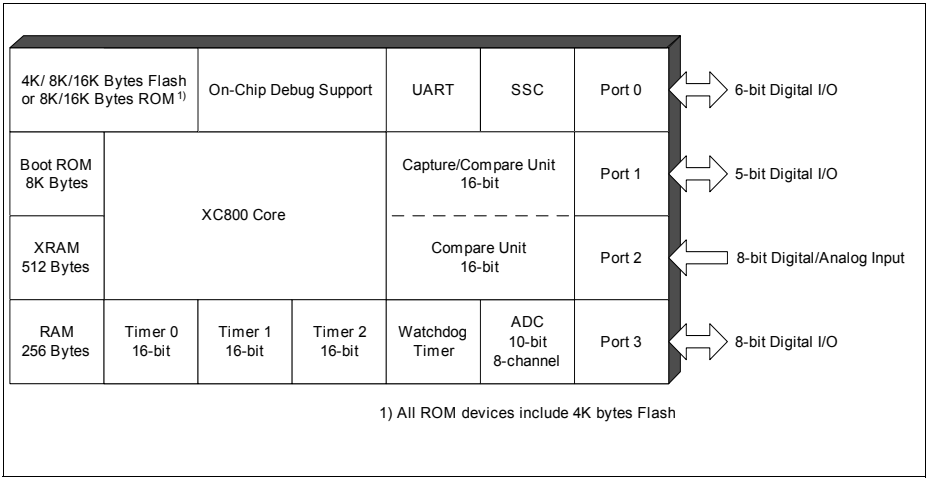


Figure 1 XC866 Functional Units

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery

For the available ordering codes for the XC866, please refer to your responsible sales representative or your local distributor.

As this document refers to all the derivatives, some descriptions may not apply to a specific product. For simplicity all versions are referred to by the term XC866 throughout this document.

3.2.1 Memory Protection Strategy

The XC866 memory protection strategy includes:

- Read-out protection: The Flash Memory can be enabled for read-out protection and ROM memory is always protected.
- Program and erase protection: The Flash memory in all devices can be enabled for program and erase protection.

Flash memory protection is available in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in **Table 4**.

Table 4 Flash Protection Modes

Mode	0	1
Activation	Program a valid password via BSL mode 6	
Selection	MSB of password = 0	MSB of password = 1
P-Flash contents can be read by	Read instructions in the P-Flash	Read instructions in the P-Flash or D-Flash
P-Flash program and erase	Not possible	Not possible
D-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash or D-Flash
D-Flash program	Possible	Not possible
D-Flash erase	Possible, on the condition that bit DFLASHEN in register MISC_CON is set to 1 prior to each erase operation	Not possible

BSL mode 6, which is used for enabling Flash protection, can also be used for disabling Flash protection. Here, the programmed password must be provided by the user. A password match triggers an automatic erase of the read-protected Flash contents, see **Table 5** and **Table 6**, and the programmed password is erased. The Flash protection is then disabled upon the next reset.

For XC866-2FR and XC866-4FR devices:

The selection of protection type is summarized in **Table 5**.

3.2.2 Special Function Register

The Special Function Registers (SFRs) occupy direct internal data memory space in the range 80_H to FF_H. All registers, except the program counter, reside in the SFR area. The SFRs include pointers and registers that provide an interface between the CPU and the on-chip peripherals. As the 128-SFR range is less than the total number of registers required, address extension mechanisms are required to increase the number of addressable SFRs. The address extension mechanisms include:

- Mapping
- Paging

3.2.2.1 Address Extension by Mapping

Address extension is performed at the system level by mapping. The SFR area is extended into two portions: the standard (non-mapped) SFR area and the mapped SFR area. Each portion supports the same address range 80_H to FF_H, bringing the number of addressable SFRs to 256. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit RMAP in the system control register SYSCON0 at address $8F_H$. To access SFRs in the mapped area, bit RMAP in SFR SYSCON0 must be set. Alternatively, the SFRs in the standard area can be accessed by clearing bit RMAP. The SFR area can be selected as shown in **Figure 8**.

SYSCON0
System Control Register 0 **Reset Value: 00_H**

7	6	5	4	3	2	1	0
0					**1**	**0**	**RMAP**
r					rw	r	rw

Field	Bits	Type	Description
RMAP	0	rw	**Special Function Register Map Control** 0 The access to the standard SFR area is enabled. 1 The access to the mapped SFR area is enabled.
1	2	rw	**Reserved** Returns the last value if read; should be written with 1.
0	1,[7:3]	r	**Reserved** Returns 0 if read; should be written with 0.

Table 10 Port Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$B1_H$	**P3_ALTSEL1** **Reset: 00_H** P3 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 3										
80_H	**P0_OD** **Reset: 00_H** P0 Open Drain Control Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_OD** **Reset: 00_H** P1 Open Drain Control Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$B0_H$	**P3_OD** **Reset: 00_H** P3 Open Drain Control Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 11 ADC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$D1_H$	**ADC_PAGE** **Reset: 00_H** Page Register for ADC	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
CA_H	**ADC_GLOBCTR** **Reset: 30_H** Global Control Register	Bit Field	ANON	DW	CTC		0			
		Type	rw	rw	rw		r			
CB_H	**ADC_GLOBSTR** **Reset: 00_H** Global Status Register	Bit Field	0		CHNR			0	SAMPLE	BUSY
		Type	r		rh			r	rh	rh
CC_H	**ADC_PRAR** **Reset: 00_H** Priority and Arbitration Register	Bit Field	ASEN1	ASEN0	0	ARBM	CSM1	PRIO1	CSM0	PRIO0
		Type	rw	rw	r	rw	rw	rw	rw	rw
CD_H	**ADC_LCBR** **Reset: $B7_H$** Limit Check Boundary Register	Bit Field	BOUND1				BOUND0			
		Type	rw				rw			
CE_H	**ADC_INPCR0** **Reset: 00_H** Input Class Register 0	Bit Field	STC							
		Type	rw							
CF_H	**ADC_ETRCR** **Reset: 00_H** External Trigger Control Register	Bit Field	SYNEN1	SYNEN0	ETRSEL1			ETRSEL0		
		Type	rw	rw	rw			rw		
RMAP = 0, Page 1										
CA_H	**ADC_CHCTR0** **Reset: 00_H** Channel Control Register 0	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CB_H	**ADC_CHCTR1** **Reset: 00_H** Channel Control Register 1	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CC_H	**ADC_CHCTR2** **Reset: 00_H** Channel Control Register 2	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CD_H	**ADC_CHCTR3** **Reset: 00_H** Channel Control Register 3	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CE_H	**ADC_CHCTR4** **Reset: 00_H** Channel Control Register 4	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
CF_H	**ADC_CHCTR5** **Reset: 00_H** Channel Control Register 5	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
$D2_H$	**ADC_CHCTR6** **Reset: 00_H** Channel Control Register 6	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
$D3_H$	**ADC_CHCTR7** **Reset: 00_H** Channel Control Register 7	Bit Field	0	LCC			0	RESRSEL		
		Type	r	rw			r	rw		
RMAP = 0, Page 2										

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
CA_H	**ADC_CHINFR** **Reset: 00_H** Channel Interrupt Flag Register	Bit Field	CHINF 7	CHINF 6	CHINF 5	CHINF 4	CHINF 3	CHINF 2	CHINF 1	CHINF 0
		Type	rh	rh	rh	rh	rh	rh	rh	rh
CB_H	**ADC_CHINCR** **Reset: 00_H** Channel Interrupt Clear Register	Bit Field	CHINC 7	CHINC 6	CHINC 5	CHINC 4	CHINC 3	CHINC 2	CHINC 1	CHINC 0
		Type	w	w	w	w	w	w	w	w
CC_H	**ADC_CHINSR** **Reset: 00_H** Channel Interrupt Set Register	Bit Field	CHINS 7	CHINS 6	CHINS 5	CHINS 4	CHINS 3	CHINS 2	CHINS 1	CHINS 0
		Type	w	w	w	w	w	w	w	w
CD_H	**ADC_CHINPR** **Reset: 00_H** Channel Interrupt Node Pointer Register	Bit Field	CHINP 7	CHINP 6	CHINP 5	CHINP 4	CHINP 3	CHINP 2	CHINP 1	CHINP 0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
CE_H	**ADC_EVINFR** **Reset: 00_H** Event Interrupt Flag Register	Bit Field	EVINF 7	EVINF 6	EVINF 5	EVINF 4	0		EVINF 1	EVINF 0
		Type	rh	rh	rh	rh	r		rh	rh
CF_H	**ADC_EVINCR** **Reset: 00_H** Event Interrupt Clear Flag Register	Bit Field	EVINC 7	EVINC 6	EVINC 5	EVINC 4	0		EVINC 1	EVINC 0
		Type	w	w	w	w	r		w	w
$D2_H$	**ADC_EVINSR** **Reset: 00_H** Event Interrupt Set Flag Register	Bit Field	EVINS 7	EVINS 6	EVINS 5	EVINS 4	0		EVINS 1	EVINS 0
		Type	w	w	w	w	r		w	w
$D3_H$	**ADC_EVINPR** **Reset: 00_H** Event Interrupt Node Pointer Register	Bit Field	EVINP 7	EVINP 6	EVINP 5	EVINP 4	0		EVINP 1	EVINP 0
		Type	rw	rw	rw	rw	r		rw	rw
RMAP = 0, Page 6										
CA_H	**ADC_CRCR1** **Reset: 00_H** Conversion Request Control Register 1	Bit Field	CH7	CH6	CH5	CH4	0			
		Type	rwh	rwh	rwh	rwh	r			
CB_H	**ADC_CRPR1** **Reset: 00_H** Conversion Request Pending Register 1	Bit Field	CHP7	CHP6	CHP5	CHP4	0			
		Type	rwh	rwh	rwh	rwh	r			
CC_H	**ADC_CRMR1** **Reset: 00_H** Conversion Request Mode Register 1	Bit Field	Rsv	LDEV	CLR PND	SCAN	ENSI	ENTR	ENGT	
		Type	r	w	w	rw	rw	rw	rw	
CD_H	**ADC_QMR0** **Reset: 00_H** Queue Mode Register 0	Bit Field	CEV	TREV	FLUSH	CLRV	TRMD	ENTR	ENGT	
		Type	w	w	w	w	rw	rw	rw	
CE_H	**ADC_QSR0** **Reset: 20_H** Queue Status Register 0	Bit Field	Rsv	0	EMPTY	EV	0			
		Type	r	r	rh	rh	r			
CF_H	**ADC_Q0R0** **Reset: 00_H** Queue 0 Register 0	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
$D2_H$	**ADC_QBUR0** **Reset: 00_H** Queue Backup Register 0	Bit Field	EXTR	ENSI	RF	V	0	REQCHNR		
		Type	rh	rh	rh	rh	r	rh		
$D2_H$	**ADC_QINR0** **Reset: 00_H** Queue Input Register 0	Bit Field	EXTR	ENSI	RF	0		REQCHNR		
		Type	w	w	w	r		w		

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 12 Timer 2 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$C0_H$	**T2_T2CON** **Reset: 00_H** Timer 2 Control Register	Bit Field	TF2	EXF2	0		EXEN2	TR2	0	$\overline{CP}$/ $\overline{RL2}$
		Type	rwh	rwh	r		rw	rwh	r	rw

Table 12 Timer 2 Register Overview (cont'd)

$C1_H$	**T2_T2MOD** **Reset: 00_H** Timer 2 Mode Register	Bit Field	T2 REGS	T2 RHEN	EDGE SEL	PREN	T2PRE		DCEN
		Type	rw	rw	rw	rw	rw		rw
$C2_H$	**T2_RC2L** **Reset: 00_H** Timer 2 Reload/Capture Register Low	Bit Field	RC2[7:0]						
		Type	rwh						
$C3_H$	**T2_RC2H** **Reset: 00_H** Timer 2 Reload/Capture Register High	Bit Field	RC2[15:8]						
		Type	rwh						
$C4_H$	**T2_T2L** **Reset: 00_H** Timer 2 Register Low	Bit Field	THL2[7:0]						
		Type	rwh						
$C5_H$	**T2_T2H** **Reset: 00_H** Timer 2 Register High	Bit Field	THL2[15:8]						
		Type	rwh						

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 13 CCU6 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$A3_H$	**CCU6_PAGE** **Reset: 00_H** Page Register for CCU6	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
$9A_H$	**CCU6_CC63SRL** **Reset: 00_H** Capture/Compare Shadow Register for Channel CC63 Low	Bit Field	CC63SL							
		Type	rw							
$9B_H$	**CCU6_CC63SRH** **Reset: 00_H** Capture/Compare Shadow Register for Channel CC63 High	Bit Field	CC63SH							
		Type	rw							
$9C_H$	**CCU6_TCTR4L** **Reset: 00_H** Timer Control Register 4 Low	Bit Field	T12 STD	T12 STR	0		DTRES	T12 RES	T12RS	T12RR
		Type	w	w	r		w	w	w	w
$9D_H$	**CCU6_TCTR4H** **Reset: 00_H** Timer Control Register 4 High	Bit Field	T13 STD	T13 STR	0			T13 RES	T13RS	T13RR
		Type	w	w	r			w	w	w
$9E_H$	**CCU6_MCMOUTSL** **Reset: 00_H** Multi-Channel Mode Output Shadow Register Low	Bit Field	STRM CM	0	MCMPS					
		Type	w	r	rw					
$9F_H$	**CCU6_MCMOUTSH** **Reset: 00_H** Multi-Channel Mode Output Shadow Register High	Bit Field	STRHP	0	CURHS			EXPHS		
		Type	w	r	rw			rw		
$A4_H$	**CCU6_ISRL** **Reset: 00_H** Capture/Compare Interrupt Status Reset Register Low	Bit Field	RT12P M	RT12O M	RCC62 F	RCC62 R	RCC61 F	RCC61 R	RCC60 F	RCC60 R
		Type	w	w	w	w	w	w	w	w
$A5_H$	**CCU6_ISRH** **Reset: 00_H** Capture/Compare Interrupt Status Reset Register High	Bit Field	RSTR	RIDLE	RWHE	RCHE	0	RTRPF	RT13 PM	RT13 CM
		Type	w	w	w	w	r	w	w	w
$A6_H$	**CCU6_CMPMODIFL** **Reset: 00_H** Compare State Modification Register Low	Bit Field	0	MCC63 S	0			MCC62 S	MCC61 S	MCC60 S
		Type	r	w	r			w	w	w
$A7_H$	**CCU6_CMPMODIFH** **Reset: 00_H** Compare State Modification Register High	Bit Field	0	MCC63 R	0			MCC62 R	MCC61 R	MCC60 R
		Type	r	w	r			w	w	w
FA_H	**CCU6_CC60SRL** **Reset: 00_H** Capture/Compare Shadow Register for Channel CC60 Low	Bit Field	CC60SL							
		Type	rwh							

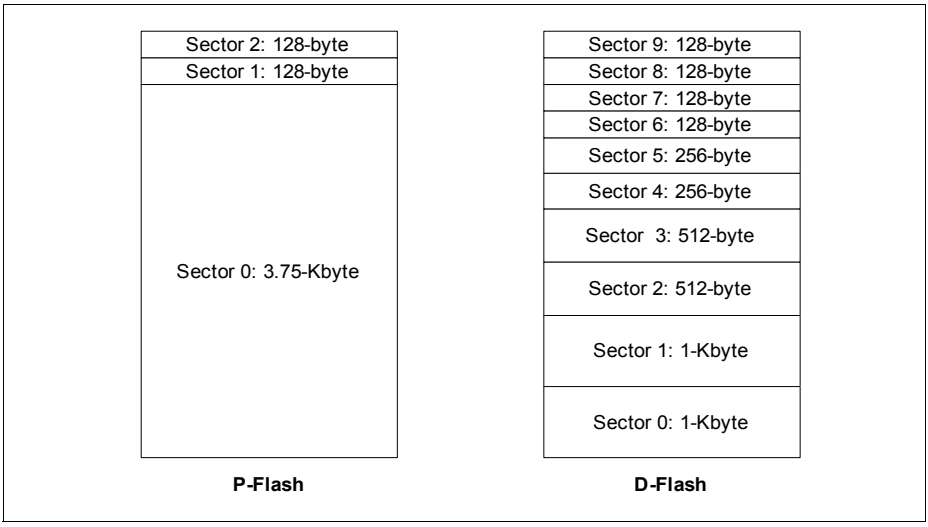


Figure 11 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

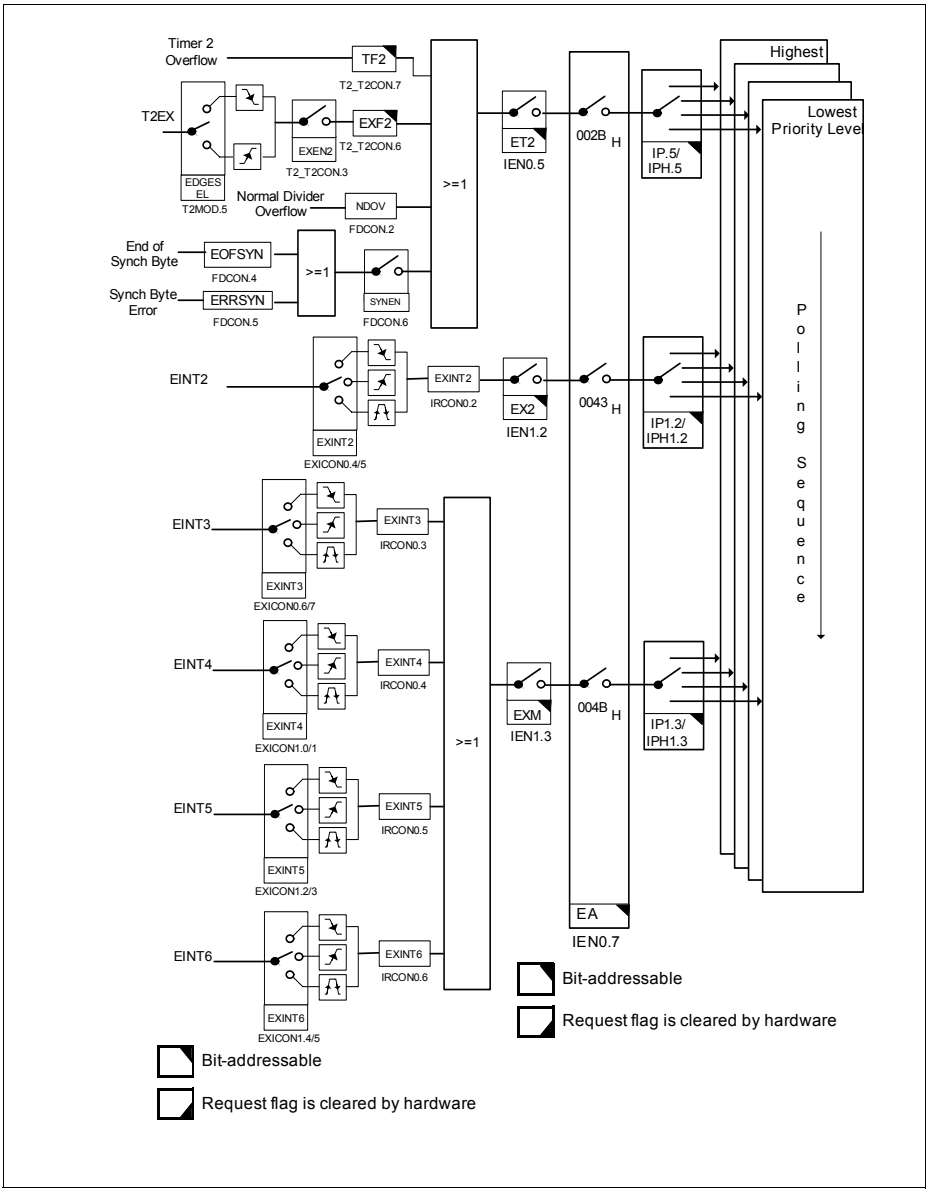


Figure 15 Interrupt Request Sources (Part 2)

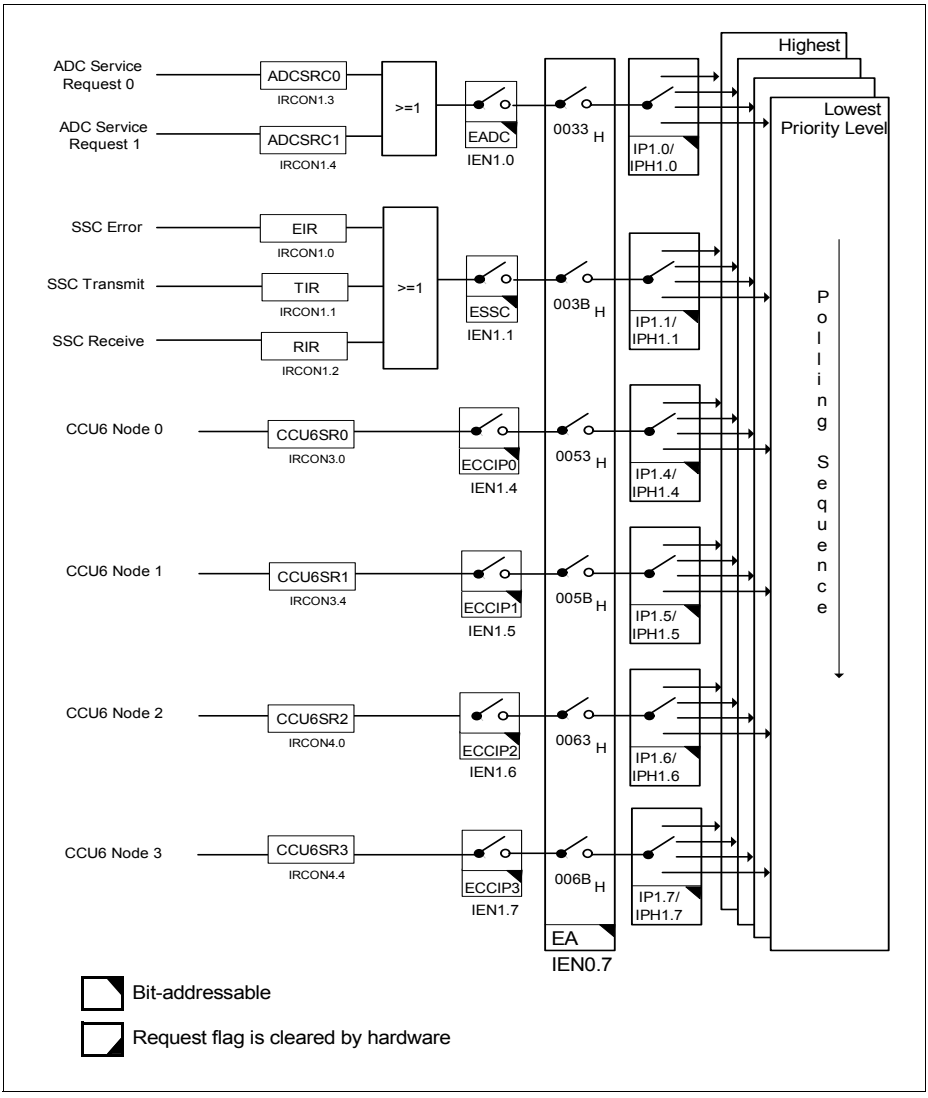


Figure 16 Interrupt Request Sources (Part 3)

Table 17 Interrupt Vector Addresses (cont'd)

XINTR6	0033_H	ADC	EADC	IEN1
XINTR7	$003B_H$	SSC	ESSC	
XINTR8	0043_H	External Interrupt 2	EX2	
XINTR9	$004B_H$	External Interrupt 3	EXM	
		External Interrupt 4		
		External Interrupt 5		
		External Interrupt 6		
XINTR10	0053_H	CCU6 INP0	ECCIP0	
XINTR11	$005B_H$	CCU6 INP1	ECCIP1	
XINTR12	0063_H	CCU6 INP2	ECCIP2	
XINTR13	$006B_H$	CCU6 INP3	ECCIP3	

The clock system provides three ways to generate the system clock:

PLL Base Mode

The system clock is derived from the VCO base (free running) frequency clock divided by the K factor.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

PLL Mode

The system clock is derived from the oscillator clock, multiplied by the N factor, and divided by the P and K factors. Both VCO bypass and PLL bypass must be inactive for this PLL mode. The PLL mode is used during normal system operation. .

$$f_{SYS} = f_{OSC} \times \frac{N}{P \times K}$$

Table 3-1 shows the settings of bits OSCDISC and VCOBYP for different clock mode selection.

Table 3-1 Clock Mode Selection

OSCDISC	VCOBYP	Clock Working Modes
0	0	PLL Mode
0	1	Prescaler Mode
1	0	PLL Base Mode
1	1	PLL Base Mode

Note: When oscillator clock is disconnected from PLL, the clock mode is PLL Base mode regardless of the setting of VCOBYP bit.

System Frequency Selection

For the XC866, the values of P and K are fixed to “1” and “2”, respectively. In order to obtain the required system frequency, f_{sys}, the value of N can be selected by bit NDIV for different oscillator inputs. **Table 21** provides examples on how f_{sys} = 80 MHz can be obtained for the different oscillator sources.

- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where} \quad 2^{BRPRE} \times (BR\_VALUE + 1) > 1$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 26.7 MHz, the maximum achievable baud rate is 0.83 MBaud.

Standard LIN protocal can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 26 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 26.7 MHz is used.

Table 26 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2^{BRPRE})	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	87 (57_H)	-0.22 %
9600 Baud	1 (BRPRE=000_B)	174 (AE_H)	-0.22 %
4800 Baud	2 (BRPRE=001_B)	174 (AE_H)	-0.22 %
2400 Baud	4 (BRPRE=010_B)	174 (AE_H)	-0.22 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 27** lists the resulting deviation errors from generating a baud rate of

3.17 Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features:

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

Timer T13 Features:

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features:

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

3.18.1 ADC Clocking Scheme

A common module clock f_{ADC} generates the various clock signals used by the analog and digital parts of the ADC module:

- f_{ADCA} is input clock for the analog part.
- f_{ADCI} is internal clock for the analog part (defines the time base for conversion length and the sample time). This clock is generated internally in the analog part, based on the input clock f_{ADCA} to generate a correct duty cycle for the analog components.
- f_{ADCD} is input clock for the digital part.

The internal clock for the analog part f_{ADCI} is limited to a maximum frequency of 10 MHz. Therefore, the ADC clock prescaler must be programmed to a value that ensures f_{ADCI} does not exceed 10 MHz. The prescaler ratio is selected by bit field CTC in register GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.

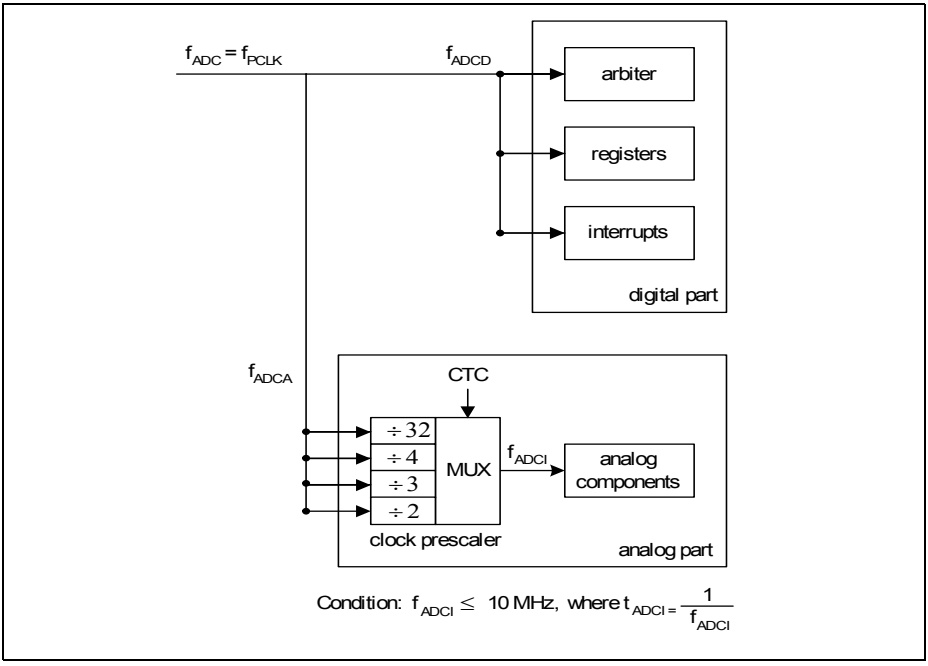


Figure 33 ADC Clocking Scheme

For module clock f_{ADC} = 26.7 MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 30**.

Table 30 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
26.7 MHz	00_B	÷ 2	13.3 MHz (N.A)
	01_B	÷ 3	8.9 MHz
	10_B	÷ 4	6.7 MHz
	11_B (default)	÷ 32	833.3 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 26.7 MHz. During slow-down mode where f_{ADC} may be reduced to 13.3 MHz, 6.7 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

3.18.2 ADC Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})

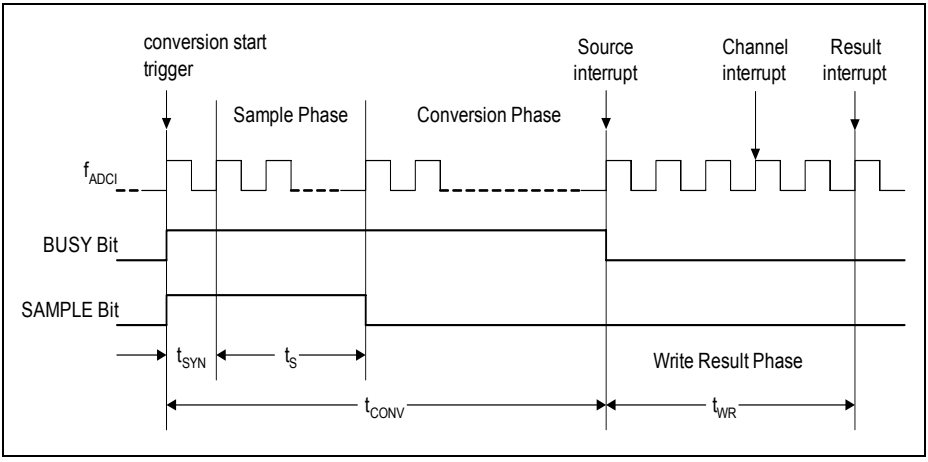


Figure 34 ADC Conversion Timing

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Conditions Remarks
		min.	max.		
Input low voltage at XTAL1	V_{ILX} SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX} SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	
Pull-up current	I_{PU} SR	–	-10	µA	$V_{IH,min}$
		-150	–	µA	$V_{IL,max}$
Pull-down current	I_{PD} SR	–	10	µA	$V_{IL,max}$
		150	–	µA	$V_{IH,min}$
Input leakage current[2)]	I_{OZ1} CC	-1	1	µA	0 < V_{IN} < V_{DDP}, $T_A \leq 125°C$, XC866-4FR and XC866-2FR
		-2.5	1	µA	0 < V_{IN} < V_{DDP}, $T_A \leq 125°C$, XC866-1FR and ROM device
Input current at XTAL1	I_{ILX} CC	-10	10	µA	
Overload current on any pin	I_{OV} SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma\|I_{OV}\|$ SR	–	25	mA	3)
Voltage on any pin during V_{DDP} power off	V_{PO} SR	–	0.3	V	4)
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma\|I_M\|$ SR	–	60	mA	
Maximum current into V_{DDP}	I_{MVDDP} SR	–	80	mA	
Maximum current out of V_{SS}	I_{MVSS} SR	–	80	mA	

Table 36 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol	Limit Values			Unit	Test Conditions/ Remarks
		min.	typ .	max.		
Switched capacitance at the analog voltage inputs	C_{AINSW} CC	–	5	7	pF	2)4)
Input resistance of the reference input	R_{AREF}CC	–	1	2	kΩ	2)
Input resistance of the selected analog channel	R_{AIN} CC	–	1	1.5	kΩ	2)

1) TUE is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V , V_{DDP} = 5.0 V.

2) Not subject to production test, verified by design/characterization.

3) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.

4) The sampling capacity of the conversion C-Network is pre-charged to V_{AREF}/2 before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than V_{AREF}/2.

Table 38 Power Down Current (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Power-Down Mode[3]	I_{PDP}	1	10	µA	T_A = + 25 °C.[4]
		-	30	µA	T_A = + 85 °C, XC866-4FR, XC866-2FR [4][5]
		-	35	µA	T_A = + 85 °C, XC866-1FR, ROM device[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 5.0 V.

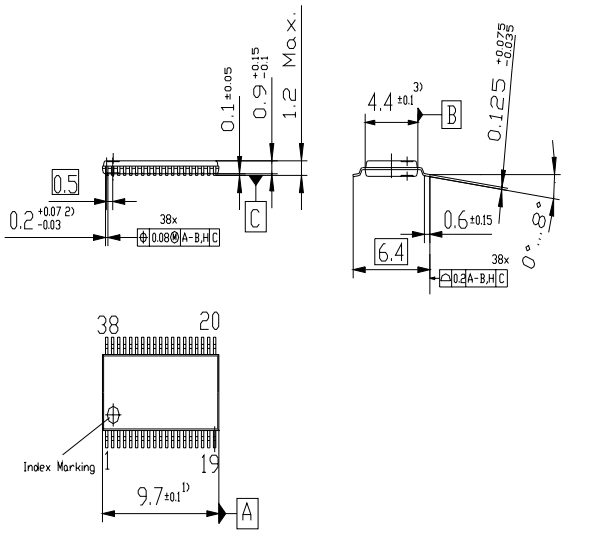
2) The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

3) I_{PDP} (power-down mode) has a maximum value of 200 µA at T_A = + 125 °C.

4) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subject to production test, verified by design/characterization.

5.2 Package Outline



1) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.15 MAX. PER SIDE

2) DOES NOT INCLUDE DAMBAR PROTRUSION OF 0.08 MAX. PER SIDE

3) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.25 MAX. PER SIDE

Figure 46 PG-TSSOP-38-4 Package Outline